

FDS3580

80V N-Channel PowerTrench® MOSFET

General Description

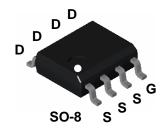
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

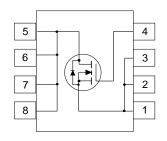
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\text{DS(ON)}}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 7.6 A, 80 V. $R_{DS(ON)} = 0.029 \ \Omega \ @ \ V_{GS} = 10 \ V$ $R_{DS(ON)} = 0.033 \ \Omega \ @ \ V_{GS} = 6 \ V.$
- Low gate charge (34nC typical).
- Fast switching speed.
- High performance trench technology for extremely low R_{DS(ON)}.
- High power and current handling capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		80	V
V _{GSS}	Gate-Source Voltage		<u>+</u> 20	V
I _D	Drain Current - Continuous	(Note 1a)	7.6	А
	- Pulsed		50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{stg}	Operating and Storage Junction Temperature Range		-55 to +150	∘C

Thermal Characteristics

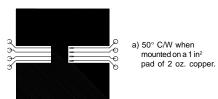
$R_{\theta^{JA}}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	∘C/W
R ₀ JC	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

Package Outlines and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDS3580	FDS3580	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	urce Avalanche Ratings (Note 2)					
W_{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 40 \text{ V}, I_D = 7.6 \text{ A}$			245	mJ
I _{AR}	Maximum Drain-Source Avalanche Cu	urrent			7.6	Α
Off Char	acteristics		•	!		•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	80			V
ΔBV _{DSS} ΔT ₁	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		81		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 64 V, V _{GS} = 0 V			1	μД
I _{GSSF}	Gate-Body Leakage, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Chara	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2	2.5	4	V
$\Delta V_{GS(th)}$ ΔT_{\perp}	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		-7		mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 7.6 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 7.6 \text{ A}, T_J = 125^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 7 \text{ A}$		0.022 0.037 0.024	0.029 0.055 0.033	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	30			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 7.6 \text{ A}$		28		S
Dvnamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		1800		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		180		pF
C _{rss}	Reverse Transfer Capacitance			90		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 40 \text{ V}, I_{D} = 1 \text{ A},$		13	26	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_{GEN} = 6 Ω		8	20	ns
t _{d(off)}	Turn-Off Delay Time	1		34	60	ns
t _f	Turn-Off Fall Time	1		16	30	ns
Q _g	Total Gate Charge	$V_{DS} = 40 \text{ V}, I_{D} = 7.6 \text{ A},$		34	46	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		6.1		nC
Q_{gd}	Gate-Drain Charge			6.9		nC
Drain-Sດ	urce Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source D	_			2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.1 \text{ A}$ (Note 2)		0.74	1.2	V

^{1:} $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.







Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2.0\%$

Typical Characteristics

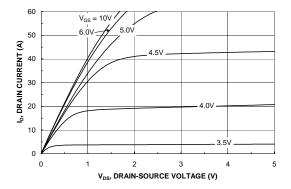


Figure 1. On-Region Characteristics.

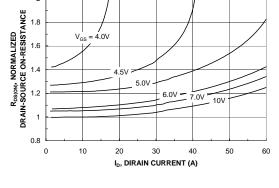


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

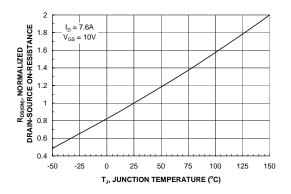


Figure 3. On-Resistance Variation with Temperature.

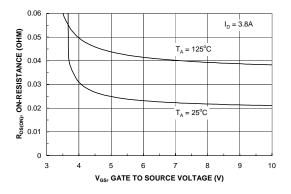


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

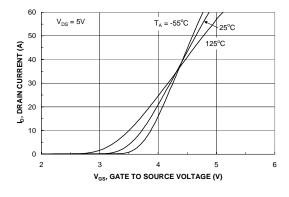


Figure 5. Transfer Characteristics.

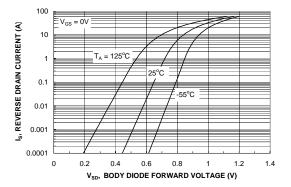
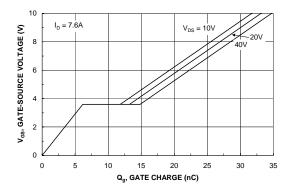


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



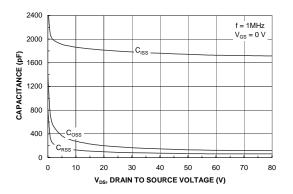
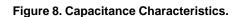
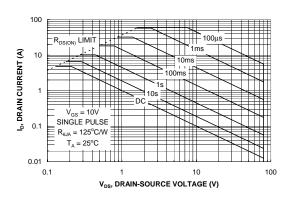


Figure 7. Gate-Charge Characteristics.





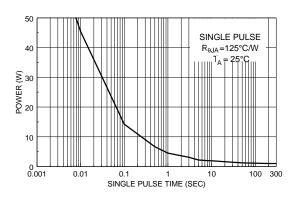


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

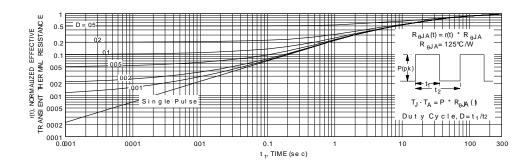


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

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